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Cc: Michelle Mullin[Mullin.Michelle@epa.gov]; Moore, Kendall[moore.kendall@epa.gov]
From: Ramanauskas, Peter
Sent: Thur 5/19/2016 7:41:06 PM
Subject: Epoxy Encapsulant ORD Study

Hi Kent,

Reaching out to you as it seems like Zhishi Guo is no longer with ORD. We're working on a caulk removal project in Region 10 where the school is looking for some guidance on the best epoxy to use as a substrate encapsulant. The attached presentation indicates that "no solvent" epoxies performed well as encapsulants. There is a preference in our situation for low/no VOC if possible.

Can you shed some more light on these "no solvent" epoxies that we can relay to the school as guidance on which they might wish to consider for use?

Thanks!

Peter